

1A1 THRU 1A7

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1.0A Axial Leaded General Purpose Rectifiers 50V-1000V

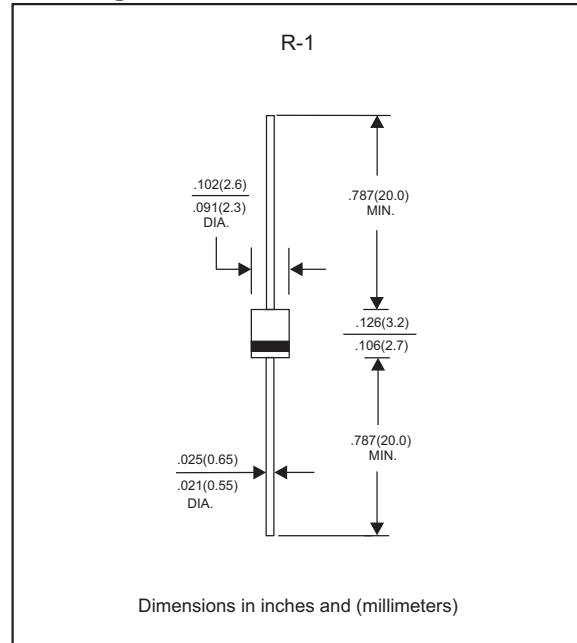
Features

- Axial lead type devices for through hole design
- High current capability
- High surge capability
- Silicon rubber coating chip junction
- Lead free parts meet RoHS requirements
- Suffix "-H" indicates Halogen-free parts, ex. 1A1-H

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, R-1
- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end
- Mounting Position : Any
- Weight : Approximated 0.19 gram

Package outline



Maximum ratings and Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	I_O			1.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			30	A
Reverse current	$V_R = V_{RRM} \quad T_J = 25^{\circ}\text{C}$	I_R			5.0	μA
	$V_R = V_{RRM} \quad T_J = 100^{\circ}\text{C}$				50	
Thermal resistance	Junction to ambient	$R_{\theta JA}$		60		$^{\circ}\text{C/W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		15		pF
Storage temperature		T_{STG}	-65		+175	$^{\circ}\text{C}$

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	Operating temperature $T_J, (^{\circ}\text{C})$
1A1	50	35	50	1.10	-55 to +125
1A2	100	70	100		
1A3	200	140	200		
1A4	400	280	400		
1A5	600	420	600		
1A6	800	560	800		
1A7	1000	700	1000		

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage@ $I_F=1.0\text{A}$

Rating and characteristic curves (1A1 THRU 1A7)

FIG.1-TYPICAL FORWARD
CHARACTERISTICS

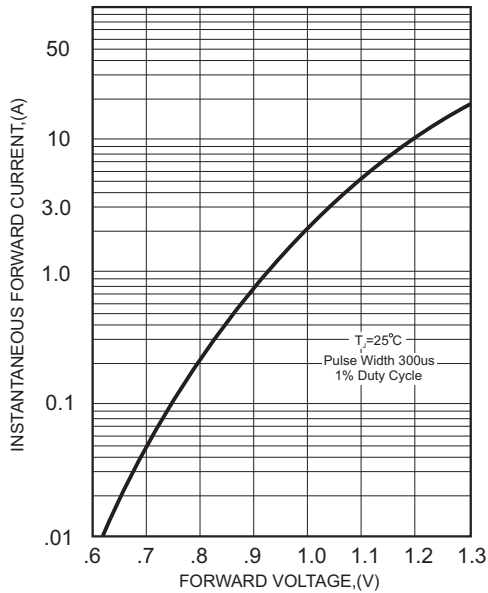


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

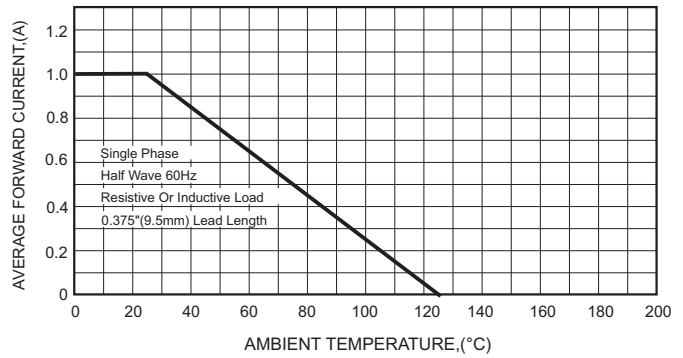


FIG.4-MAXIMUM NON-REPETITIVE FORWARD
SURGE CURRENT

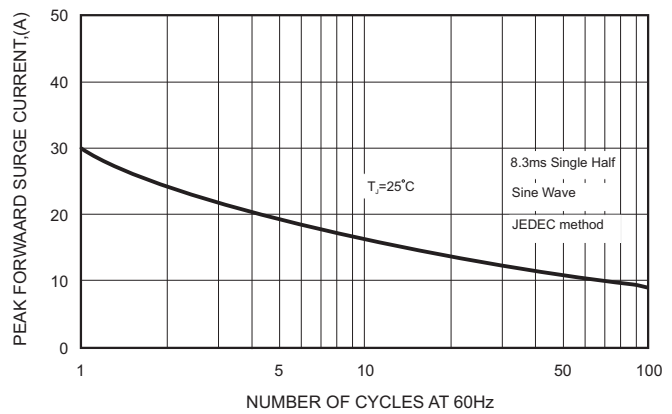


FIG.3 - TYPICAL REVERSE
CHARACTERISTICS

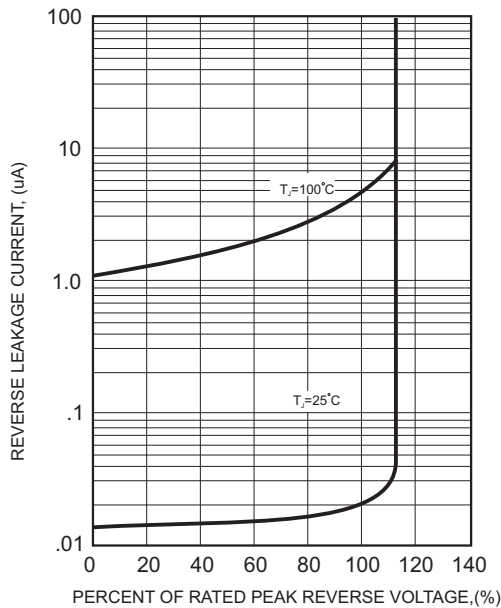
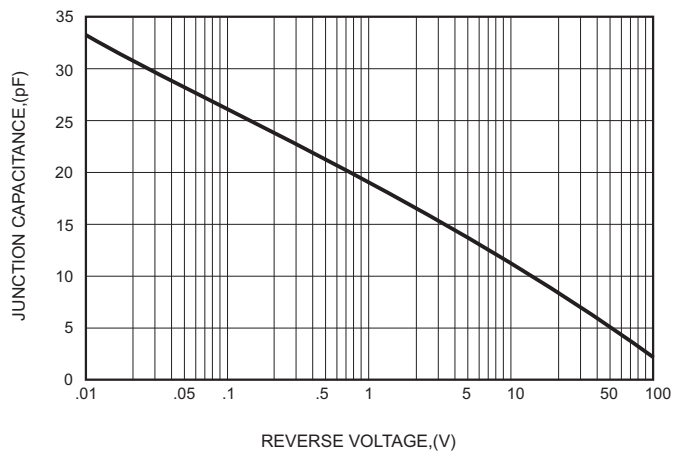


FIG.5-TYPICAL JUNCTION CAPACITANCE



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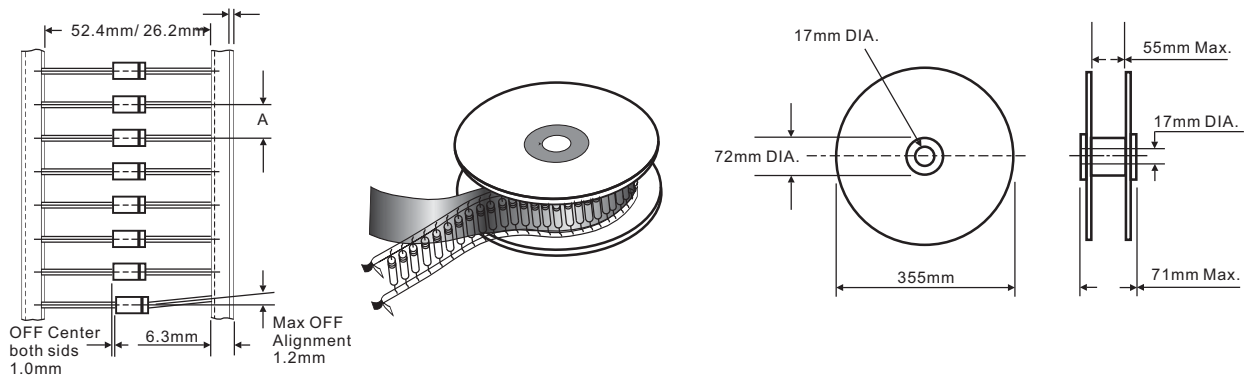
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode	1  2	1  2

Marking

Type number	Marking code
1A1	1A1
1A2	1A2
1A3	1A3
1A4	1A4
1A5	1A5
1A6	1A6
1A7	1A7

Taping & bulk specifications for AXIAL devices



REEL PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / REEL)	COMPONENT SPACING "A" in FIG. A	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
R-1/52mm	5,000	5 mm	360 * 340 * 370	20,000	7.3

AMMO PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
R-1/26mm	3,000	256 * 47 * 73	310 * 268 * 170	36,000	6.8
R-1/52mm	5,000	260 * 80 * 140	410 * 270 * 300	50,000	12.5

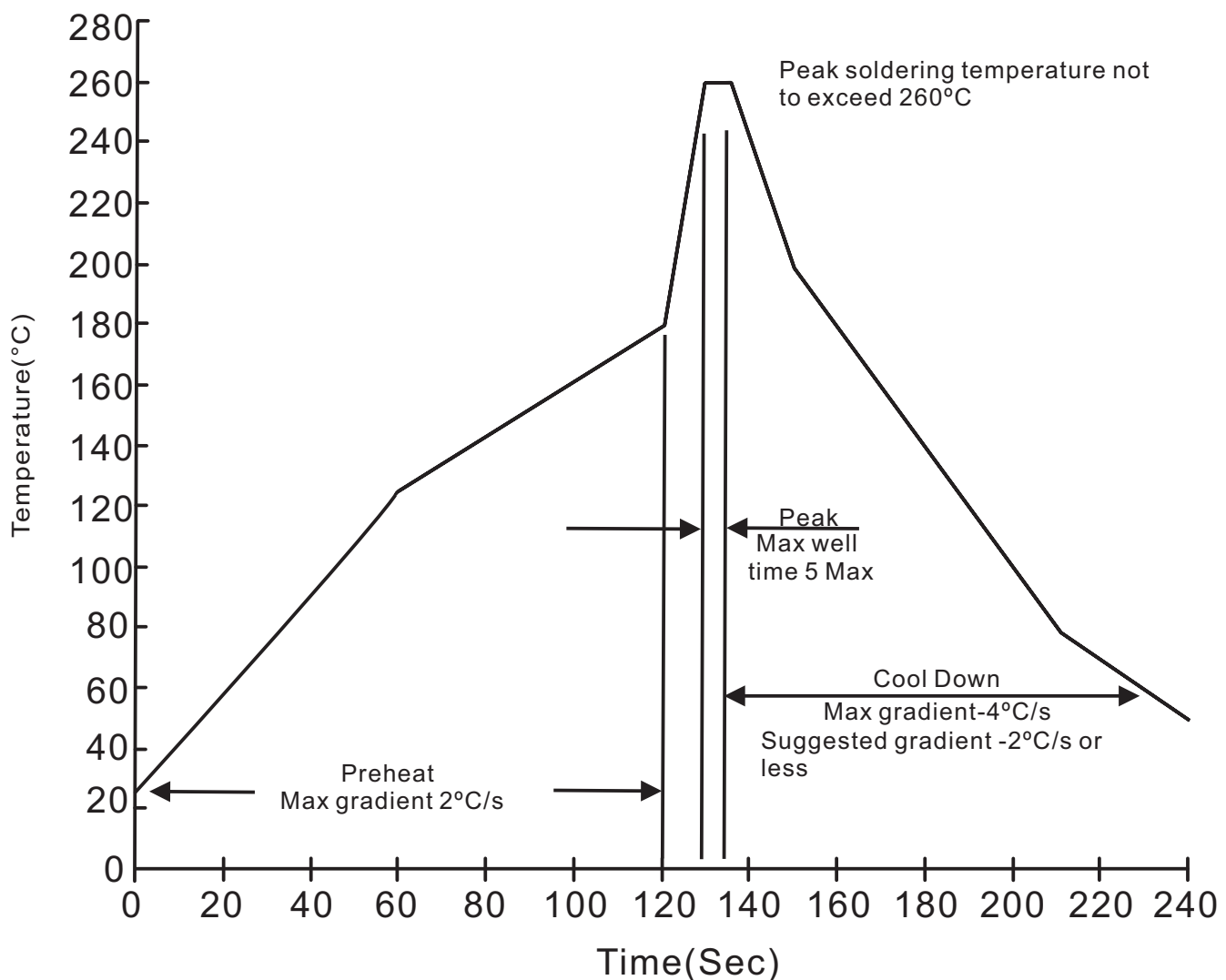
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BULK PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
R-1	1,000	194 * 84 * 20	465 * 220 * 260	50,000	12.2

Suggested thermal profiles for soldering processes

1. Lead free temperature profile wave-soldering



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High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260 \pm 5^\circ\text{C}$ for $10 \pm 2\text{sec.}$ immerse body into solder $1/16'' \pm 1/32''$	MIL-STD-750D METHOD-2031
2. Solderability	at $245 \pm 5^\circ\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. Pull Test	0.5kg in axial lead direction for 10 sec. $I_F = I_O$	MIL-STD-202F METHOD-211A
4. Bend Lead	0.5kg weight applied to each lead bending arc $90^\circ \pm 5^\circ$ for 3 times	MIL-STD-202F METHOD-211A
5. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_J = 125^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
6. Forward Operation Life	Rated average rectifier current at $T_A = 25^\circ\text{C}$ for 500hrs. $T_A = 25^\circ\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min, on and off for 500 cycles.	MIL-STD-750D METHOD-1027
7. Intermittent Operation Life		MIL-STD-750D METHOD-1036
8. Pressure Cooker	$15P_{SIG}$ at $T_A = 121^\circ\text{C}$ for 4 hrs.	JESD22-A102
9. Temperature Cycling	-55°C to $+125^\circ\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
10. Forward Surge	8.3ms single half sine-wave one surge.	MIL-STD-750D METHOD-4066-2
11. Humidity	at $T_A = 85^\circ\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
12. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031